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JC784 U.S. PTO
10/385681

To the Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
[FAMILY NAME (ALL CAPS), Given Name]
HSIEH, Han-Kun **3-12-03**
LIN, Wei-Feng
HSIEH, Yi-Chang

Additional name(s) of conveying party(ies) attached?
 YES NO

2. Name and address of receiving party(ies)
Name: **SILICON INTEGRATED SYSTEMS CORP.**
Internal Address:
Street Address: **No. 16 Creation Rd. 1, Science-Based Industrial Park**
City: **Hsinchu** State: ZIP:
Country: **TAIWAN, R.O.C.** Postal Code:
Additional name(s) & address(es) attached? YES NO

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other:
Execution Date: **February 25, 2003; February 25, 2003; and February 27, 2003, respectively.**

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: **February 25, 2003; February 25, 2003; and February 27, 2003, respectively.**

A. Patent Application No(s). **NEW** **10385681**
B. Patent No.(s).
Additional numbers attached? YES NO

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: **BIRCH, STEWART, KOLASCH & BIRCH, LLP**
Street Address: **P.O. BOX 747**
City: **FALLS CHURCH** State: **VA** ZIP: **22040-0747**
Country: **USA**

6. Total No. of applications/patents involved: **ONE (1)**
7. Total fee (37 C.F.R. § 3.41): **\$40.00**
 Enclosed
 Authorized to be charged to deposit account, **if no fee attached.**
8. Deposit account number: **02-2448**

(Attach triplicate copy of this page if paying by deposit account)

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9. Statement and signature.
Joe McKinney Muncy, #32,334 **James T. Elliff, #39,538**
Name of Person Signing/Reg. No. Signature Date
March 12, 2003
Date

Total number of pages including cover sheet, attachments, and document: **TWO (2)**

KM/ka

(Rev.12/31/2002)

ASSIGNMENT

WHEREAS, Han-Kun HSIEH, Wei-Feng LIN and Yi-Chang HSIEH hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CHIP-PACKAGING SUBSTRATE AND TEST METHOD THEREFOR
 Filed: March 12, 2003 Serial No. NEW
 Executed on: February 25, 2003; February 25, 2003; and Feb. 27, 2003, respectively

WHEREAS, Silicon Integrated Systems Corp. of No.16, Creation Rd. 1, Science-Based Industrial Park, Hsin chu, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Han-kun Hsieh
 Han-Kun HSIEH

2003. 2. 25
 Date:

Wei-Feng Lin
 Wei-Feng LIN

2003. 2. 25
 Date:

Yi Chang Hsieh
 Yi-Chang HSIEH

2/27/03'
 Date: